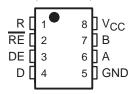
- High-Speed Low-Power LinBiCMOS™ Circuitry Designed for Signaling Rates[†] Up to 30 Mbps
- **Bus-Pin ESD Protection Exceeds 12 kV HBM**
- Compatible With ANSI Standard TIA/EIA-485-A and ISO 8482:1987(E)
- Low Skew
- **Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments**
- **Very Low Disabled Supply-Current** Requirements . . . 700 µA Maximum
- Common Mode Voltage Range of -7 V to 12 V
- **Thermal-Shutdown Protection**
- **Driver Positive and Negative Current** Limiting
- **Open-Circuit Fail-Safe Receiver Design**
- Receiver Input Sensitivity . . . ±200 mV Max
- Receiver Input Hysteresis . . . 50 mV Typ
- Glitch-Free Power-Up and Power-Down **Protection**
- **Available in Q-Temp Automotive High Reliability Automotive Applications Configuration Control / Print Support Qualification to Automotive Standards**

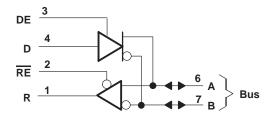
description

The SN65LBC176A, SN65LBC176AQ, and SN75LBC176A differential bus transceivers are monolithic, integrated circuits designed for bidirectional data communication on multipoint bus-transmission lines. They are designed for balanced transmission lines and are compatible with ANSI standard TIA/EIA-485-A and ISO 8482. The A version offers improved switching performance over its predecessors without sacrificing significantly more power.

SN65LBC176AQD (Marked as B176AQ) SN65LBC176AD (Marked as BL176A) SN65LBC176AP (Marked as 65LBC176A) SN75LBC176AD (Marked as LB176A) SN75LBC176AP (Marked as 75LBC176A) (TOP VIEW)



logic diagram (positive logic)



Function Tables

DRIVER

INPUT	ENABLE	OUTPUTS
D	DE	A B
Н	Н	H L
L	Н	L H
X	L	Z Z
Open	Н	H L

RECEIVER

DIFFERENTIAL INPUTS VA-VB	ENABLE RE	OUTPUT R
V _{ID} ≥ 0.2 V	L	Н
-0.2 V < V _{ID} < 0.2 V	L	?
V _{ID} ≤ −0.2 V	L	L
X	Н	Z
Open	L	Н

H = high level, L = low level,? = indeterminate, X = irrelevant,Z = high impedance (off)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

† Signaling rate by TIA/EIA-485-A definition restrict transition times to 30% of the bit length, and much higher signaling rates may be achieved without this requirement as displayed in the TYPICAL CHARACTERISTICS of this device.

LinBiCMOS and LinASIC are trademarks of Texas Instruments.



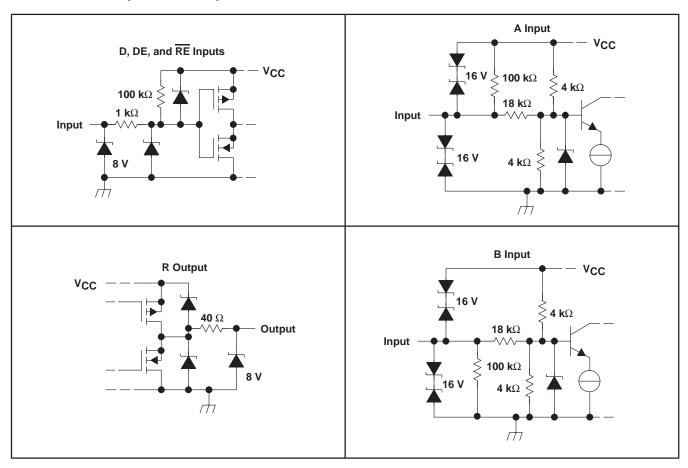
description (continued)

The SN65LBC176A, SN65LBC176AQ, and SN75LBC176A combine a 3-state, differential line driver and a differential input line receiver, both of which operate from a single 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, which can externally connect together to function as a direction control. The driver differential outputs and the receiver differential inputs connect internally to form a differential input/output (I/O) bus port that is designed to offer minimum loading to the bus whenever the driver is disabled or $V_{CC} = 0$. This port features wide positive and negative common-mode voltage ranges, making the device suitable for party-line applications. Very low device supply current can be achieved by disabling the driver and the receiver.

AVAILABLE OPTIONS

	P/	ACKAGE
TA	SMALL OUTLINE (D)	PLASTIC DUAL-IN-LINE
0°C to 70°C	SN75LBC176AD	SN75LBC176AP
-40°C to 85°C	SN65LBC176AD	SN65LBC176AP
-40°C to 125°C	SN65LBC176AQD	_

schematics of inputs and outputs





absolute maximum ratings†

Supply voltage, V _{CC} (see Note 1)	0.3 V to 6 V
Voltage range at any bus terminal (A or B)	–10 V to 15 V
Input voltage, V _I (D, DE, R, or RE)	\dots -0.3 V to V _{CC} + 0.5 V
Electrostatic discharge: Bus terminals and GND, Class 3, A: (see Note 2)	
Bus terminals and GND, Class 3, B: (see Note 2)	400 V
All terminals, Class 3, A:	3 kV
All terminals, Class 3, B:	400 V
Continuous total power dissipation (see Note 3)	See Dissipation Rating Table
Storage temperature range, T _{stg}	65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential I/O bus voltage, are with respect to network ground terminal.

- 2. The maximum operating junction temperature is internally limited. Use the dissipation rating table to operate below this temperature.
- 3. Tested in accordance with MIL-STD-883C, Method 3015.7

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR‡ ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING	T _A = 125°C POWER RATING
D	725 mW	5.8 mW/°C	464 mW	377 mW	145 mW
Р	1000 mW	8.0 mW/°C	640 mW	520 mW	_

[‡] This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.75	5	5.25	V	
Voltage at any hypercurinal (apparetal), an apparent and	A. M. an M			12	V
Voltage at any bus terminal (separately or common mode	e), vi or viC	-7			V
High-level input voltage, VIH (output recessive)	D, DE, and RE	2		VCC	V
Low-level input voltage, V _{IL} (output dominant)	D, DE, and RE	0		8.0	V
Differential input voltage, V _{ID} (see Note 4)		-12§		12	V
	Driver	-60			
High-level output current, I _{OH}	Receiver	-8			mA
	Driver			60	
Low-level output current, IOL	Receiver			8	mA
	SN65LBC176AQ	-40		125	
Operating free-air temperature, TA	SN65LBC176A	-40		85	°C
	SN75LBC176A	0		70	

[§] The algebraic convention, in which the least positive (most negative) limit is designated as minimum, is used in this data sheet. NOTE 4: Differential input/output bus voltage is measured at the noninverting terminal A with respect to the inverting terminal B.



SN65LBC176A, SN75LBC176A DIFFERENTIAL BUS TRANSCEIVERS

SLLS376C-MAY 2000 - REVISED DECEMBER 2000

driver electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER		TEST CONDITIONS	6	MIN	TYP [†]	MAX	UNIT
VIK	Input clamp voltage	$I_{I} = -18 \text{ mA}$				-0.8		V
				SN65LBC176AQ	1.5	4	6	
		IO = 0		SN65LBC176A, SN75LBC176A		4		V
				SN65LBC176AQ	0.9	1.5	6	
Vop	Differential output voltage	$R_L = 54 \Omega$,	See Figure 1	SN65LBC176A	1	1.5	3	V
. 05				SN75LBC176A	1.1	1.5	3	V
				SN65LBC176AQ	0.9	1.5	6	V
		$V_{test} = -7 \text{ V to}$	12 V, See Figure 2	SN65LBC176A	1	1.5	3	V
				SN75LBC176A	1.1	1.5	3	V
Δ V _{OD}	Change in magnitude of differential output voltage	See Figures 1 and 2					0.2	V
		SN65LBC176AQ			1.8	2.4	3	
VOC(SS) Steady-state common-mod output voltage		SN		SN65LBC176A, SN75LBC176A	1.8	2.4	2.8	.,
	Change in steady-state	See Figure 1	See Figure 1		-0.2		0.2	V
Δ VOC(SS)	common-mode output voltage†			SN65LBC176A, SN75LBC176A	-0.1		0.1	
loz	High-impedance output current	See receiver inp	out currents					
lіН	High-level enable input current	V _I = 2 V						μА
Iμ	Low-level enable input current	V _I = 0.8 V						μΑ
Ios	Short-circuit output current	-7 V ≤ V _O ≤ 12 V				±70	250	mA
			Receiver disabled and	d driver enabled		5	9	
ICC	Supply current	V _I = 0 or V _{CC} , Receiver disabled and		d driver disabled	0.4 0.7		mA	
			Receiver enabled and driver enabled				15	

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.

driver switching characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST	SN65LBC176AQ			SN65LBC176A SN75LBC176A			UNIT
		CONDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	
tPLH	Propagation delay time, low-to-high-level output		2		12	2	6	12	ns
tPHL	Propagation delay time, high-to-low-level output	$R_1 = 54 \Omega$,	2		12	2	6	12	ns
tsk(p)	Pulse skew (t _{PLH} - t _{PHL})	$C_{L} = 50 \text{ pF},$			2		0.3	1	ns
t _r	Differential output signal rise time	See Figure 3	1.2		11	4	7.5	11	ns
tf	Differential output signal fall time]	1.2		11	4	7.5	11	ns
^t PZH	Propagation delay time, high-impedance-to-high-level output	$R_L = 110 \Omega$, See Figure 4			22		12	22	ns
tPZL	Propagation delay time, high-impedance-to-low-level output	$R_L = 110 \Omega$, See Figure 5			25		12	22	ns
^t PHZ	Propagation delay time, high-level-to-high- impedance output	$R_L = 110 \Omega$, See Figure 4			22		12	22	ns
t _{PLZ}	Propagation delay time, low-level-to-high-impedance output	R _L = 110 Ω , See Figure 5	·	·	22		12	22	ns

 $^{^{\}dagger}$ All typical values are at V_{CC} = 5 V, T_A = 25°C.



receiver electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER		TEST CONDITION	IS	MIN	TYP [†]	MAX	UNIT
V _{IT+}	Positive-going input threshold voltage	$I_O = -8 \text{ mA}$					0.2	V
VIT-	Negative-going input threshold voltage	I _O = 8 mA			-0.2			V
V _{hys}	Hysteresis voltage (V _{IT+} - V _{IT-})					50		mV
VIK	Enable-input clamp voltage	I _I = –18 mA			-1.5	-0.8		V
Vон	High-level output voltage	$V_{ID} = 200 \text{ mV},$	$I_{OH} = -8 \text{ mA},$	See Figure 6	4	4.9		V
VOL	Low-level output voltage	$V_{ID} = 200 \text{ mV},$	I _{OL} = 8 mA,	See Figure 6		0.1	8.0	V
				SN65LBC176AQ	-10		10	
loz	High-impedance-state output current	$V_O = 0$ to V_{CC}		SN65LBC176A, SN75LBC176A	-1		1	μΑ
		V _{IH} = 12 V,	V _{CC} = 5 V			0.4	1	
	Bus insulations	V _{IH} = 12 V,	VCC = 0	Other terror at 0.14		0.5	1	4
11	Bus input current	$V_{IH} = -7 V$,	V _{CC} = 5 V	Other input at 0 V	-0.8	-0.4		mA
		$V_{IH} = -7 V$,	VCC = 0]	-0.8	-0.3		
lіН	High-level enable-input current	V _{IH} = 2 V						μΑ
IIL	Low-level enable-input current	V _{IL} = 0.8 V			-100			μΑ
			Receiver enabled a	nd driver disabled		4	7	
ICC	Supply current	V _I = 0 or V _{CC} , No load Receiver disabled and driver disabled			0.4	0.7	mA	
		110 1000	Receiver enabled and driver enabled				15	

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

receiver switching characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	SN65LBC176AQ			SN65LBC176A SN75LBC176A			UNIT
			MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	
t _{PLH}	Propagation delay time, output↑		7		30	7	13	20	ns
tPHL	Propagation delay time, output↓	V _{ID} = -1.5 V to 1.5 V, See Figure 7	7		30	7	13	20	ns
tsk(p)	Pulse skew (tpHL -tpLH)	Occ riguic 7			6		0.5	1.5	ns
t _r	Rise time, output	Coo Figure 7			5		2.1	3.3	ns
tf	Fall time, output	See Figure 7			5		2.1	3.3	ns
^t PZH	Output enable time to high level				50		30	45	ns
tPZL	Output enable time to low level	C _L = 10 pF,			50		30	45	ns
t _{PHZ}	Output disable time from high level	See Figure 8			60		20	40	ns
tPLZ	Output disable time from low level			-	40		20	40	ns

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.



PARAMETER MEASUREMENT INFORMATION

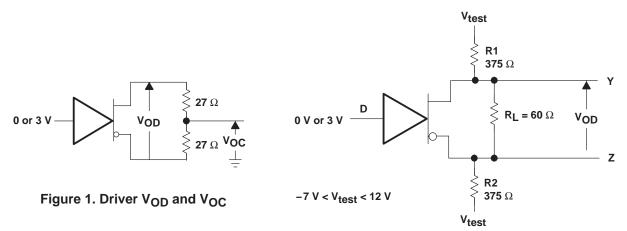
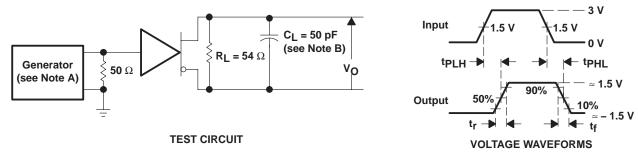
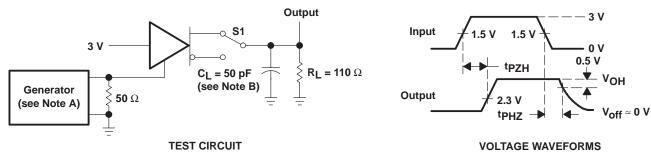


Figure 2. Driver V_{OD3}



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{f} \leq$ 6 ns, $t_{f} \leq$ 7 ns, $t_{f} \leq$ 8 ns, $t_{f} \leq$ 9 ns, $t_$
 - B. C_L includes probe and jig capacitance.

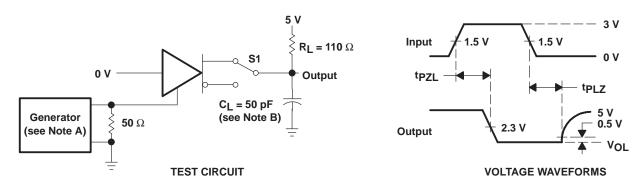
Figure 3. Driver Test Circuit and Voltage Waveforms



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{\Gamma} \leq$ 7 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 9 ns, $t_$
 - B. CL includes probe and jig capacitance.

Figure 4. Driver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_f \leq$ 6 ns, $t_f \leq$ 8 ns, $t_f \leq$ 8 ns, $t_f \leq$ 9 ns, t_f

B. C_L includes probe and jig capacitance.

Figure 5. Driver Test Circuit and Voltage Waveforms

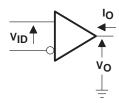
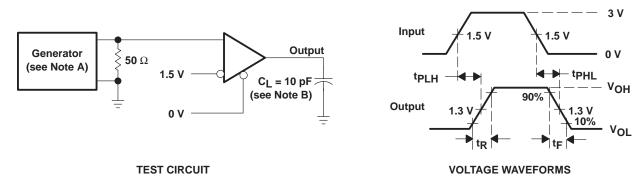


Figure 6. Receiver VOH and VOL

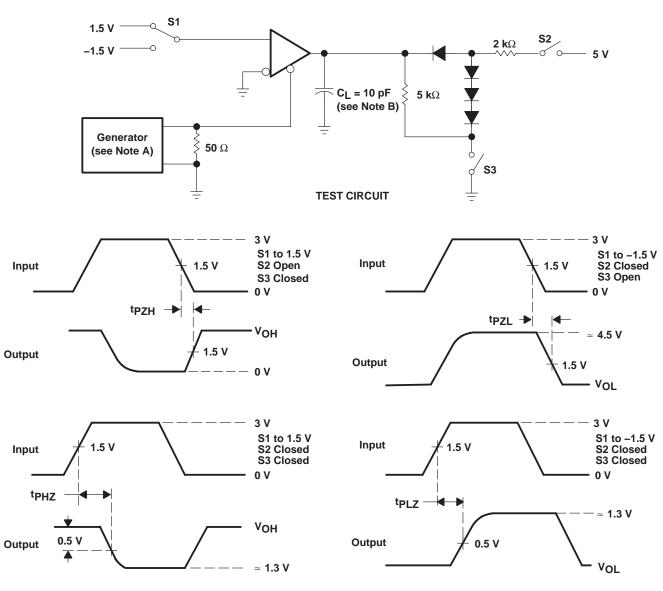


NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{\Gamma} \leq$ 7 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 9 ns, $t_$

B. C_I includes probe and jig capacitance.

Figure 7. Receiver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



VOLTAGE WAVEFORMS

NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{\Gamma} \leq$ 7 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 9 ns, $t_$

B. C_L includes probe and jig capacitance.

Figure 8. Receiver Test Circuit and Voltage Waveforms



TYPICAL CHARACTERISTICS

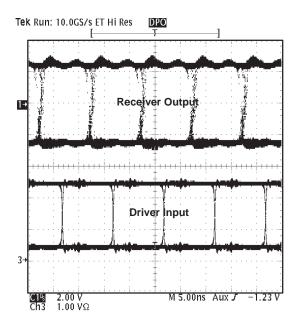




Figure 9. Typical Waveform of Non-Return-To-Zero (NRZ), Pseudorandom Binary Sequence (PRBS) Data at 100 Mbps Through 15m, of CAT 5 Unshielded Twisted Pair (UTP) Cable

TIA/EIA-485-A defines a maximum signaling rate as that in which the transition time of the voltage transition of a logic-state change remains less than or equal to 30% of the bit length. Transition times of greater length perform quite well even though they do not meet the standard by definition.

TYPICAL CHARACTERISTICS

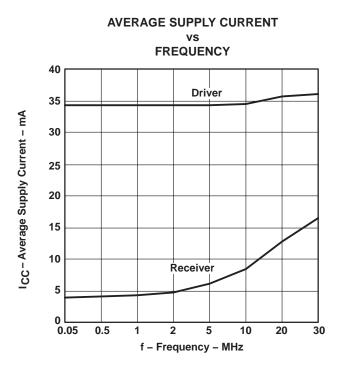


Figure 10

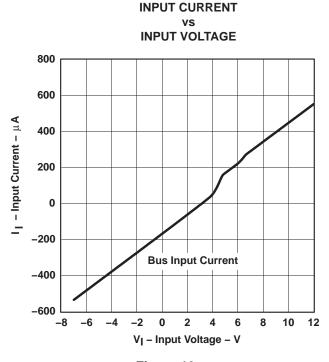


Figure 12

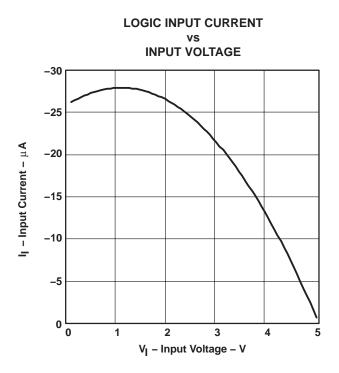
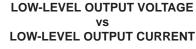


Figure 11



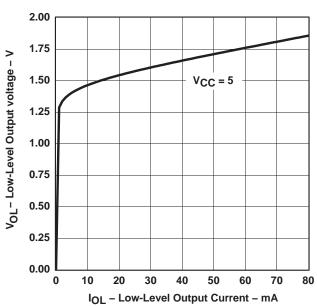


Figure 13

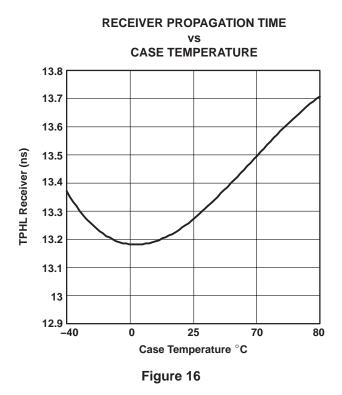
DRIVER DIFFERENTIAL OUTPUT VOLTAGE

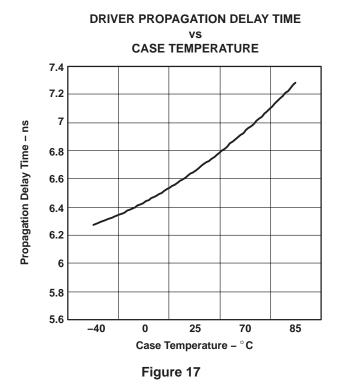
TYPICAL CHARACTERISTICS

DRIVER HIGH-LEVEL OUTPUT VOLTAGE **HIGH-LEVEL OUTPUT CURRENT** 5 4.5 VOH - High-Level Output Voltage - V V_{CC} = 5.25 V 3.5 3 2.5 $V_{CC} = 5 V$ 2 $V_{CC} = 4.75 V$ 1.5 0.5 -50 -30 -40 I_{OH} - High-Level Output Current - (mA)

Figure 14

AVERAGE CASE TEMPERATURE Average Case Temperature – °C Figure 15





TYPICAL CHARACTERISTICS

DRIVER OUTPUT CURRENT vs SUPPLY VOLTAGE

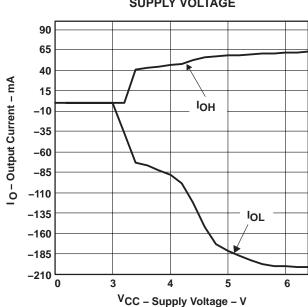


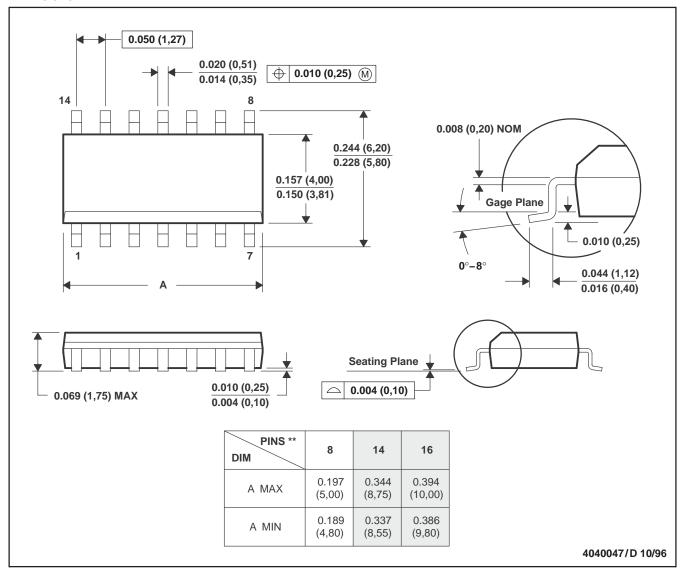
Figure 18

MECHANICAL INFORMATION

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

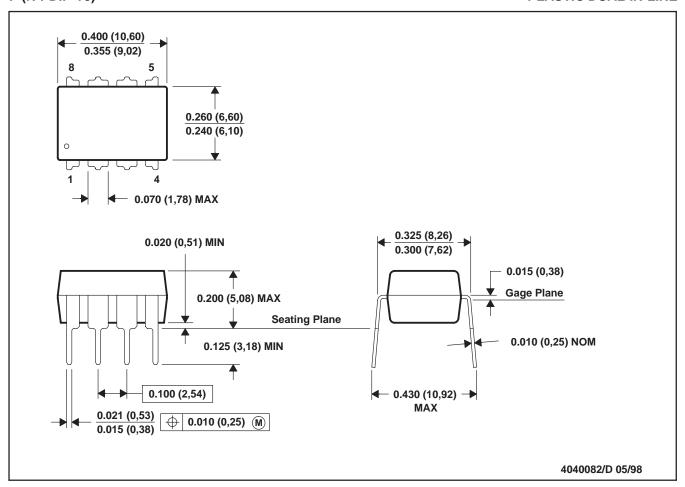
C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

MECHANICAL INFORMATION

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm







.com 4-Aug-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN65LBC176AD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LBC176ADR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LBC176ADRG4	ACTIVE	SOIC	D	8	2500	TBD	Call TI	Call TI
SN65LBC176AP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN65LBC176APE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN65LBC176AQD	ACTIVE	SOIC	D	8	75	TBD	CU NIPDAU	Level-1-220C-UNLIM
SN65LBC176AQDR	ACTIVE	SOIC	D	8	2500	TBD	CU NIPDAU	Level-1-220C-UNLIM
SN75LBC176AD	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
SN75LBC176ADR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
SN75LBC176AP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN75LBC176APE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



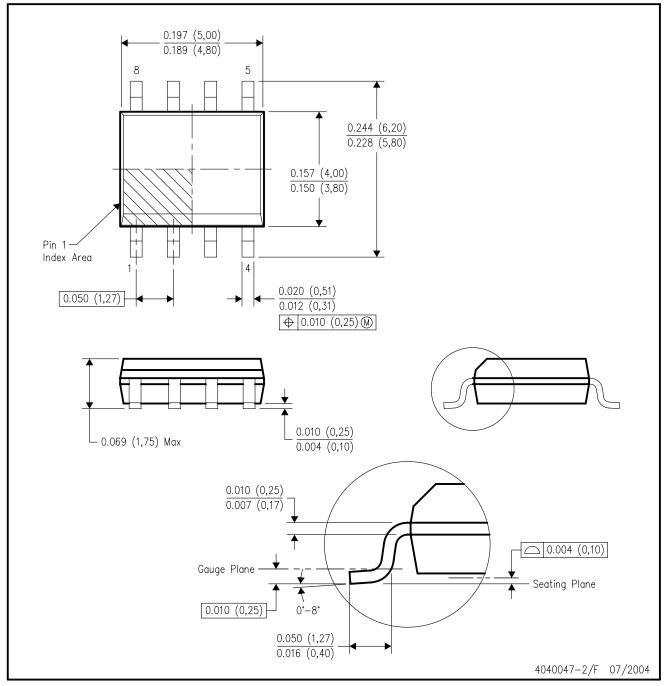
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AA.



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